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Specification MCOT128064KV-YM



DOC.

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 - 4.2: listing out definitely the tolerance.

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- **6.** Icons explanation

Midas 2006 version logo. Midas is an integrated manufacturer of flat panel display (FPD). Midas supplies TN, HTN, STN, FSTN monochrome LCD panel; COB, COG, TAB LCD module; and all kinds of LED backlight.



FAST RESPONSE TIME

This icon on the cover indicates the product is with high response speed; Otherwise not.



PROTECTION CIRCUIT

This icon on the cover indicates the product is with protection circuit; Otherwise not.



HIGH CONTRAST

This icon on the cover indicates the product is with high contrast; Otherwise not.



LONG LIFE VERSION

This icon on the cover indicates the product is long life version (over 9K hours guaranteed); Otherwise not.



WIDE VIEWING SCOPE

This icon on the cover indicates the product is with wide viewing scope; Otherwise not.



Anti UV VERSION

This icon on the cover indicates the product is against UV line. Otherwise not.



RoHS COMPLIANCE

This icon on the cover indicates the product meets ROHS requirements; Otherwise not.



OPERATION TEMPERATURE RANGE

This icon on the cover indicates the operating temperature range (X-Y).



3TIMEs 100% QC EXAMINATION

This icon on the cover indicates the product has passed Midas thrice 100% QC.
Otherwise not.



TWICE SELECTION OF LED MATERIALS

This icon on the cover indicates the LED had passed Midas twice strict selection which promises the product's identical color and brightness; Otherwise not.



Vicm = 3.0V

This icon on the cover indicates the product can work at 3.0V exactly; otherwise not.



N SERIES TECHNOLOGY (2008 developed)

New structure, new craft, new technology and new materials inside both LCD module and LCD panel to improve the "RainBow"

Midas Displays OLED Part Number System

•		_		•	J	Ü	10
1	=	MCO:	Midas Displays OLED				
2	=	Blank:	B: COB (Chip on Board) T: TAB	(Taped Automated	Bonding)		
3	=	No of dots:	(e.g. 240064 = 240 x 64 dots)	(e.g. 21605 = 2 x	16 5mm C.H.)		
4	=	Series	A to Z				
5	=	Series Variant:	A to Z and 1 to 9 – see addendum				
6	=	Operat <mark>ing</mark> T <mark>emp Range:</mark>	A: -3 0+85° C V: -4 <mark>0+8</mark> 0° C	Y: -40 +70° C	Z: -30+70° C		

I: I2C

B: Blue

X: -40 +85° C

Y: Yellow

P: Parallel

e.g. 3 = 3v

Blank: Not Applicable

Character Set:

Colour:

Interface:

Voltage Variant:

MCO

1

7

8

9

10

В

2

21605

3

E: Multi European Font Set (English/Japanese - Western European (K) - Cyrillic (R))

G: Green

M: Multi

RGB: Full Colour

R: Red

S: SPI

Ε

9

10

1.Revision History

VERSION	REVISED PAGE NO.	Note
1		First issue

2. General Specification

The Features is described as follow:

■ Module dimension: 82.7 ×40.2 × 3.4 (max.) mm³

■ View area: 63.41 x 32.69 mm²

■ Active area:61.41 × 30.69 mm²

■ Number of dots: 128 x 64

■ Pixel size: 0.48x 0.48 mm²

■ Pixel pitch: 0.45 x 0.45 mm2

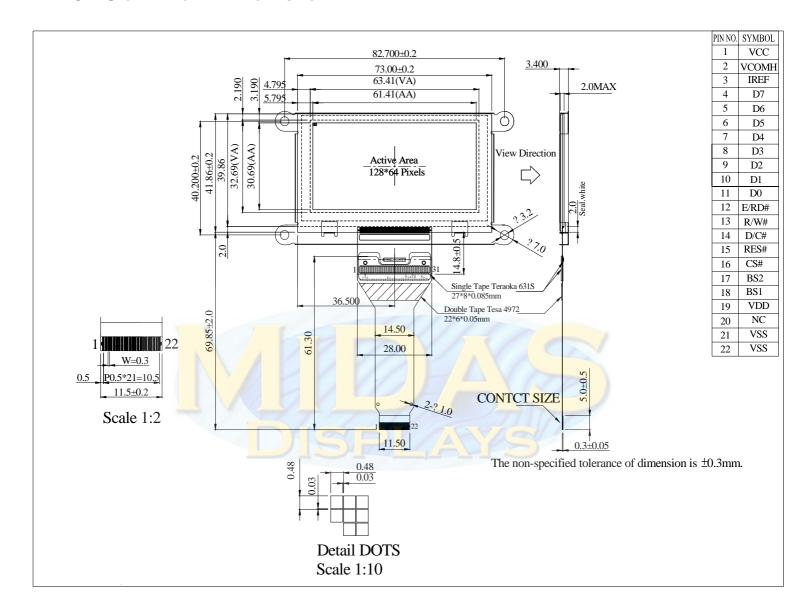
■ Duty: 1/64

■ Emitting Color: Yellow

4. Interface Pin Function

No.	Symbol	Functi	ion						
1	VCC	Power	Power supply for analog circuit.						
		Com V	/oltage Output.	A capacitor sho	uld be				
2	VCOMH	conne	cted						
		betwee	en this pin and '	VSS.					
	IREF	Refere	ence current inp	ut pin.					
3		A resis	stor should be c	onnected betwe	een this p	oin			
		and VS	SS.						
4~11	D7~D0	Data b	us.						
12	E/RD#	Data r	ead operation is	s initiated when	it's pull le	ow.			
13	R/W#	Data v	vrite operation i	s initiated when	it's pull l	ow.			
		Data/	Command cont	rol.					
14	D/C#	Pull hi	gh for write/rea	d display data.					
		Pull lo	w fo <mark>r write com</mark>	mand or read s	tatus.				
		Reset	<mark>s</mark> ign <mark>al i</mark> nput.	MAKE					
15	RES#	When	<mark>it</mark> 's l <mark>ow</mark> , initiali <mark>za</mark>	ation <mark>of SSD</mark> 130	0 <mark>5</mark> is				
		execu	ted.						
16	CS#	Chip s	elect input.	MAY					
		Comm	nunicating Proto	col Select					
17	BS2	These	pins are MCU	interface select	ion input	. See			
		the							
		followi	ng table:						
			68XX-paralle	80XX-paralle	Serial				
18	BS1		1	1					
		BS1	0	1	0				
		BS2	1	1	0				
19	VDD	Power	supply for logic	circuit.					
20	NC	No connection.							
21	VSS	Ground.							
22	VSS	Groun	d.						

5. Outline Dimension



6. Optics & Electrical Characteristics

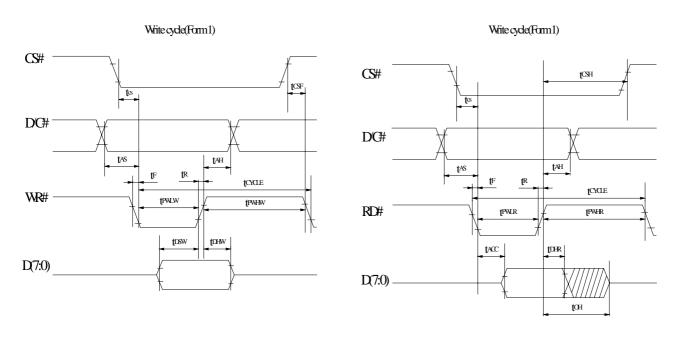
6.1INTERFACE TIMING CHART

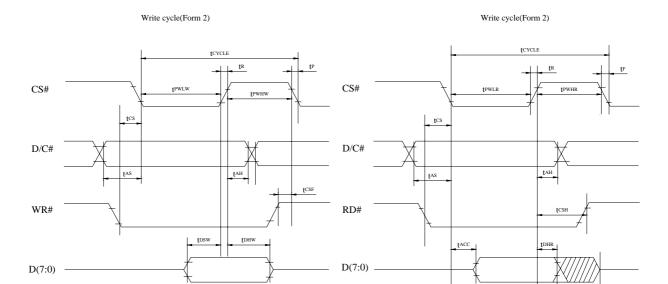
8080-Series MCU Parallel Interface Timing Characteristics

(VDD-VSS=2.4V to 3.5V, VDDIO=VDD,TA=25°C)

Symbol	Parameter	Min	Тур	Max	Unit
tcycle	Clock Cycle Time	300	-	-	ns
tAS	Address Setup Time	10	-	-	ns
tAH	Address Hold Time	0	-	-	ns
tDSW	Write Data Setup Time	40	-	-	ns
tDHW	Write Data Hold Time	7	-	-	ns
tDHR	Read Data Hold Time	20	-	-	ns
tOH	Output Disable Time	-	-	70	ns
tACC	Access Time	-	-	140	ns
tPWLR	Read Low Time	120	-	-	ns
tPWLW	Write Low Time	60	-	-	ns
tPWHR	Read High Time	60	-	-	ns
tPWHW	Write High Time	60	-	-	ns
tR	Rise Time	\- /	5-6	15	ns
tF	Fall Time		/ - \	15	ns
tCS	Chip select setup time	0	4	V->	ns
tCSH	Chip select setup hold time to read signal	0		No	ns
tCSF	Chip select setup hold time	20	C-P	(and	ns

8080-seriesparallel interface characteristics (Form 1)





6.2 DC Characteristics

Characteristics	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD		2.4	2.7	3.5	V
Supply Voltage for Display	vcc	YOF	14.5	15	<mark>15</mark> .5	V
High Level Input	VIH	lout = 100µA,3.3MHz	0.8×VDD	T	VDD	V
Low Level Input	VIL	lout = 100μA,3.3MHz	0		0.2×VDD	V
High Level Output	VOH	lout =100µA,3.3MHZ	0.9×VDD	_	VDD	V
Low Level Input	VOL	lout =100µA,3.3MHZ	0	_	0.1×VDD	V
Operating Current for VDD	IDD	Note 4	_	250	400	μΑ
Epotating Carronic for VEE	100	Note 5	_	250	400	μΑ
On a ratio a Course at fair VCC	100	Note 4	_	31	39	mA
Operating Current for VCC	ICC	Note 5	_	53	66	mA
Sleep Mode Current for VDD	IDD, SLEEP		_	_	10	μA
Sleep Mode Current for VCC	ICC, SLEEP		_	_	10	μΑ

Note 3: Brightness (Lbr) and Supply Voltage for Display (VCC) are subject to the change of the panel characteristics and the customer's request.

Note 4: VDD = 2.7V, VCC = 15V, 50% Display Area Turn on.

Note 5: VDD = 2.7V, VCC = 15V, 100% Display Area Turn on.

^{*} Software configuration follows Section 4.4 Initialization.

7. Block Diagram

7.1.POWER ON/OFF SEQUENCE & APPLICATION CIRCUIT

3.1.1 POWER ON/OFF SEQUENCE

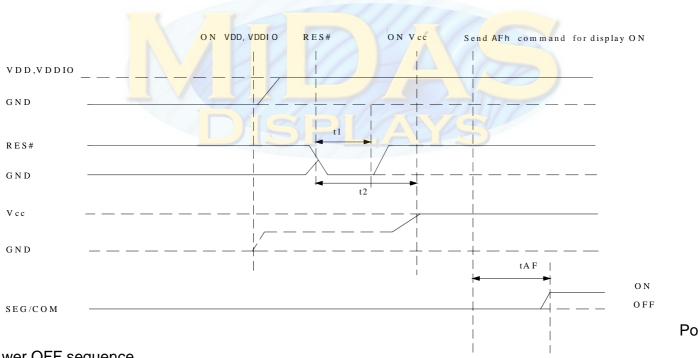
Power ON sequence

Power ON VDD, VDDIO

After VDD , VDDIO become stable , set RES# pin LOW (logic low) for at least 3us(t1) and then HIGH (logic high).

After set RES# pin LOW (logic low), wait for at least 3us(t2). Then Power ON Vcc. (1)

After Vcc. become stable, send command AFh for display ON. DEG/COM will be ON after 100ms(tAF).

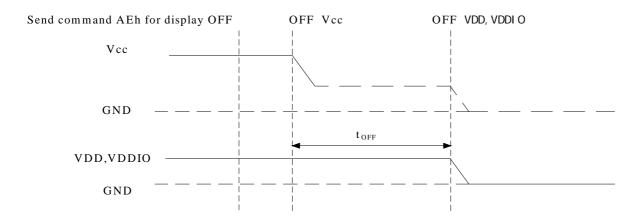


wer OFF sequence

Send command AEh for display OFF.

Power OFF Vcc.(1),(2)

Wait for tOFF. Power OFF VDD , VDDIO. (where Minimum tOFF=80ms, Typical tOFF=100ms)

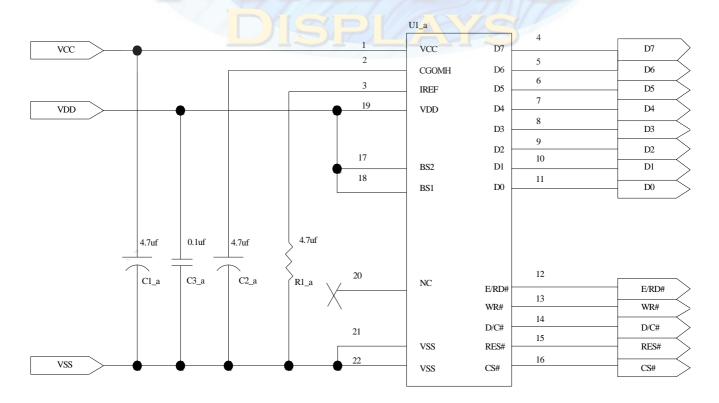


Note:

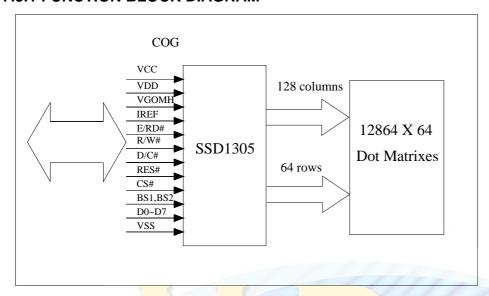
Since an ESD protection circuit is connected between VDD ,VDDIO and Vcc, Vcc becomes lower than VDD and VDD , VDDIO is ON and Vcc is OFF as shown in the dotted line of Vcc in above figures.

Vcc should be disabled when it is OFF.

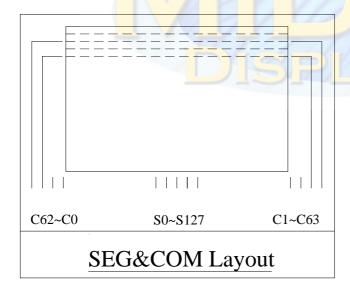
7.2 APPLICATION CIRCUIT



7.3 INTERFACE 7.3.1 FUNCTION BLOCK DIAGRAM



7.4 PANEL LAYOUT DIAGRAM



7.5 GRAPHIC DISPLAY DATA RAM ADDRESS MAP

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 132x64=8448bits

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software.

					_								
		0	0	0	0	Q	0	0	0	0	0	0	0
		SEG0	SEG0	SEG0	SEG0	SEG0	SEG0	SEG0	SEG0	 SEG0	SEG0	SEG0	SEG0
		\sigma	S	S	S	S	S	S	S	$ \mathbf{x} $	$ \mathbf{x} $	\sigma	$ \mathbf{x} $
								_	_				
		0x83h	0x82h	0x81h	0x80h	0x7Fh	0x7Eh	0x7Dh	0x7Ch	0x03h	0x02h	0x01h	0x00h
		8×0	0x8	8x0	8X	0x7	0x7	0x7	0x7	0x0)x()X	0x0
			_	_	_	_		_	_	_	_	_	\vdash
		<u>ب</u>	Ч	ζh.	3h	댐	j.	9h	'h	l (lh	ų,	3h
		0x00h	0x01h	0x02h	0x03h	0x04h	0x05h	0x06h	0x07h	0x80h	0x81h	0x82h	0x83h
		0	0	0	0	0	0	0	0	0	0	0	0
COM0 0x3Fh 0x00h	D	00											
COM1 0x3Eh 0x01h	_	1											
COM2 0x3Dh 0x02h		2											
COM3 0x3Ch 0x03h P	AUL U)3											
COM4 0x3Bh 0x04h		04											
COM5 0x3Ah 0x05h		5											-
COM6 0x39h 0x06h		06							/	_ (V
COM7 0x38h 0x07h		7											
COM8 0x37h 0x08h		00			7	7			-//		-		
COM9 0x36h 0x09h		01								~			
COM10 0x35h 0x0Ah)2											
COM11 0x34h 0x0Bh P	ALGE I	3											
)4			1	1				11			
COM13 0x32h 0x0Dh COM14 0x31h 0x0Eh		5	X			-			1	4			
COM14 0x31h 0x0Eh 0x0Fh		6						-	1)			
COM16 0x2Fh 0x10h		7											\vdash
COM17 0x2Fh 0x10h 0x11h		00								_			\vdash
COM17 0x2En 0x11n COM18 0x2Dh 0x12h		01											\vdash
COM19 Ov2Ch Ov13h	D	03											
COM20 0x2Bh 0x14h P		04											
COM21 0x2Ah 0x15h		5											
COM22 0x29h 0x16h		6											
COM23 0x28h 0x17h		7											
l state of the sta	12	, ,			-								
COM48 0x0Fh 0x30h	D	0											
COM49 0x0Eh 0x31h		1											
COM50 0x0Dh 0x32h		2											
COM51 0x0Ch 0x33h P	110L 0 =	03											
COM52 0x0Bh 0x34h		14								igsquare			
COM53 0x0Ah 0x35h		05											
COM54 0x09h 0x36h		6											\vdash
COM55 0x08h 0x37h		7											\vdash
COM56 0x07h 0x38h		00								_			
COM57 0x06h 0x39h	D									_			
COM58 0x05h 0x3Ah		2											
COM59 0x04h 0x3Bh P		03								_			
COM60 0x03h 0x3Cll	$\overline{\nu}$	94	-							<u> </u>	\vdash		\vdash
COM61 0x02h 0x3Dh COM62 0x01h 0x3Eh		05			-					<u> </u>			\vdash
		7											
COM63 0x00h 0x3Fh	ıυ	, ,											

8. Reliability

8.1 Contents of Reliability Tests

Item	Conditions	Criteria
High Temperature Operation	80°C,240hrs	4
Low Temperature Operation	-40°C,240hrs	The energtion
High Temperature Storage	80°C,240hrs	The operation I
Low Temperature Storage	-40°C,240hrs	functions work
High Temperature/Humidity	60°C,90%RH,120hrs → -40°C 80°C	, idilotions won
Operation/ Thermal Shock	24cycles 1 hr dwell	

^{*} The samples used for the above tests do not include polarizer.

8.2 Lifetime

Parameter	Min	Тур	Max	Unit	Condition	Notes
Operating Life Time	1	60,000	1-6	Hrs	80 cd/m2, 50% Checkerboard	6

Note 6: The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

8.3 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.

^{*} No moisture condensation is observed during tests.

9. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	3.5	V	1,2
Supply Voltage for Display	VCC	8	16	V	1,2
Operating Temperature	TOP	-40	80	°C	_
Storage Temperature	TSTG	-40	80	°C	_

Note 1: All the above voltages are on the basis of "VSS = 0V".

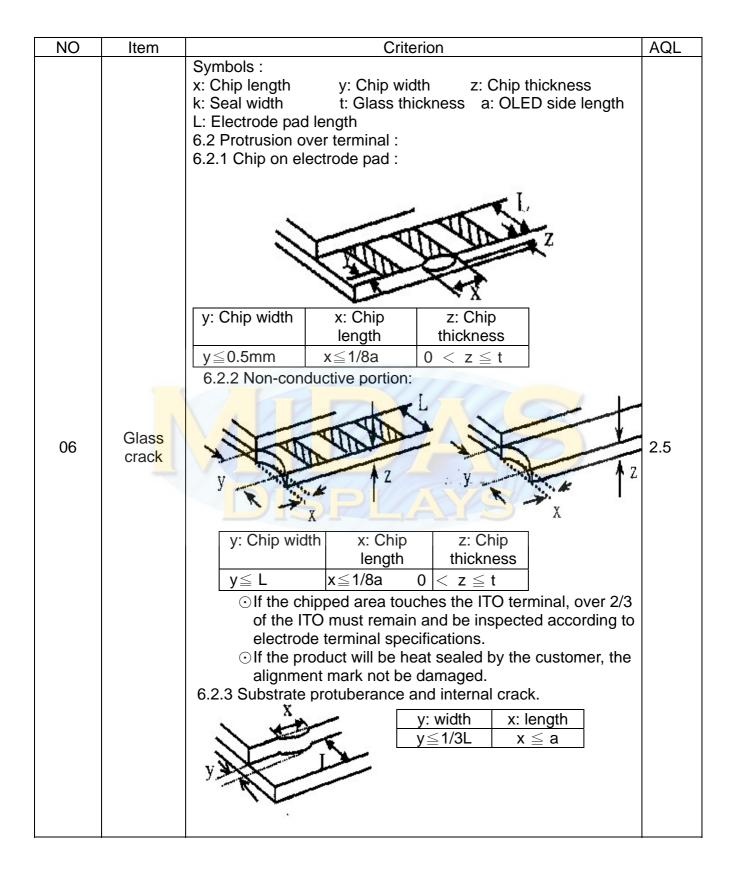
Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.



10. Inspection specification

	, •	sp e cilication		2 14 1		1 40:
NO	Item			Criterion		AQL
01	Electrical Testing	1.1 Missing vertical, 1.2 Missing characte 1.3 Display malfunct 1.4 No function or no 1.5 Current consump 1.6 Viewing angle do 1.7 Mixed product ty 1.8 Contrast defect.	er, dot or ic ion. o display. otion exce efect.	on.		0.65
02	Black or bright spots on OLED (display only)	2.1 Bright and black three Bright or bl 2.2 Densely spaced:	ack spots : No more	present. than two spots or li		2.5
03	Black spots, bright spots, contaminati on	3.1 Round type : As Φ=(x + y) / 2	siollowing	arawing		2.5
	(non-display)	3.2 Line type: (As for the line)	Length Length Lies 3.0 Lies 2.5	width W≦0.02 0.02 <w≦0.03 0.03<w≦0.05 0.05<w< td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w<></w≦0.05 </w≦0.03 	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible using black spot specifications, not e find, must check in direction.	easy to	Size Φ	Acceptable Q TY Accept no dense 3 2 0	2.5

Scratche Sollow NO.3 black spots, bright spots, contamination Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:	NO	Item	Criterion	AQL					
Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels: z: Chip thickness Z≤1/2t Not over viewing area 1/2t < z≤2t Not exceed x≤1/8a z: Chip thickness x≤1/8a y: Chip width x: Chip length x: Chip len	05		Follow NO.3 black spots, bright spots, contamination						
	06	Chipped	x: Chip length x: Chip width z: Chip thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels: 2: Chip thickness x: OLED side length x: Chip length thickness x: Chip width x: Chip length x: 1/8a x: Chip width x: Chip length of each chip. 6.1.2 Corner crack: 2: Chip y: Chip width x: Chip length of each chip. 6.1.2 Corner crack: 2: Chip thickness x: Chip length	2.5					
chip.			⊙ If there are 2 or more chips, x is the total length of each						



NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Bezel	8.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.8.2 Bezel must comply with job specifications.	2.5 0.65
9	PCB COB	 9.1 COB seal may not have pinholes larger than 0.2mm or contamination. 9.2 COB seal surface may not have pinholes through to the IC. 9.3 The height of the COB should not exceed the height indicated in the assembly diagram. 9.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 9.5 No oxidation or contamination PCB terminals. 9.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 9.7 The jumper on the PCB should conform to the product characteristic chart. 9.8 If solder gets on bezel tab pads, zebra pad or screw hold pad, make sure it is smoothed down. 9.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5 2.5
10	Soldering	 10.1 No un-melted solder paste may be present on the PCB. 10.2 No cold solder joints, missing solder connections, oxidation or icicle. 10.3 No residue or solder balls on PCB. 10.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
11	General appearance	 11.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 11.2 No cracks on interface pin (OLB) of TCP. 11.3 No contamination, solder residue or solder balls on product. 11.4 The IC on the TCP may not be damaged, circuits. 11.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 11.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 11.7 Sealant on top of the ITO circuit has not hardened. 11.8 Pin type must match type in specification sheet. 11.9 OLED pin loose or missing pins. 11.10 Product packaging must the same as specified on packaging specification sheet. 11.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

Pattern Check (Display On) in Active Area

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Pixel	Major	LAYS
Wrong Display	Major	
Un-uniform	Major	